

Device Specification

ELECTRICAL CHARACTERISTICS



Part Number	I_{hold} (A)	I_{trip} (A)	V_{max} (Vdc)	I_{max} (A)	$P_{d\ typ}$ (W)	Maximum Time To Trip		Resistance	
						Current (A)	Time (Sec.)	R_{min} (Ω)	R_{1max} (Ω)
SMD1210P110TFT	1.10	2.20	8	100	0.60	8.00	0.10	0.060	0.210

Note: I_{hold} = Hold current: maximum current device will pass without tripping in 23 °C still air.

I_{trip} = Trip current: minimum current at which the device will trip in 23 °C still air.

V_{max} = Maximum voltage device can withstand without damage at rated current (I_{max})

I_{max} = Maximum fault current device can withstand without damage at rated voltage (V_{max})

$P_{d\ typ}$ = Typical power dissipated from device when in the tripped state at 23 °C still air.

R_{min} = Minimum resistance of device in initial (un-soldered) state.

R_{1max} = Maximum resistance of device at 23 °C measured one hour after tripping or reflow soldering of 260 °C for 20 sec.

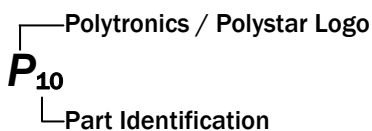
*Value specified were determined using the PWB with 0.030" * 1.5oz copper traces.

*Customer should verify the device performance in their specified conditions.

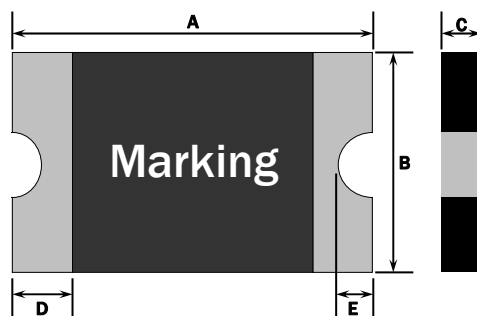
Caution: Operation beyond the specified rating may result in damage and possible arcing and flame.

Recognitions:  

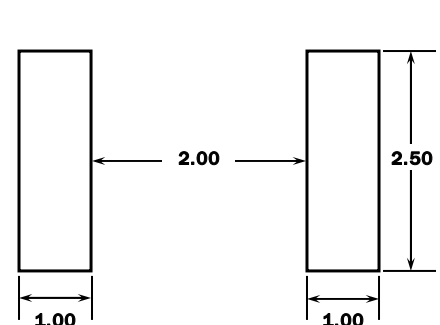
Marking



Figure



Recommended Pad Layout (mm)



Note: Polystar is Polytronics's manufacturing site in China. The Polystar ID marking shall appear on smallest package.

PHYSICAL DIMENSIONS (mm)

Part Number	A		B		C		D		E	
	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
SMD1210P110TFT	3.00	3.43	2.35	2.80	0.30	0.71	0.25	0.75	0.10	0.50

©Specifications are subject to change without notice.